



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPB020N10N5LF	<b>Issued</b>	10. June 2021
<b>MA#</b>	MA001719104		
<b>Package</b>	PG-TO263-3-2	<b>Weight*</b>	1564.93 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	7.046	0.45	0.45	4502	4502
chip_2	inorganic material	silicon	7440-21-3	0.390	0.02	0.02	249	249
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.43	19.46	194275	194528
wire	noble metal	gold	7440-57-5	0.078			50	
	non noble metal	aluminium	7429-90-5	12.395	0.79	0.79	7920	7970
encapsulation	inorganic material	zinc oxide	1314-13-2	6.761	0.43		4320	
	miscellaneous	miscellaneous	-	27.044	1.73		17281	
	plastics	epoxy resin	-	101.415	6.48		64805	
	inorganic material	silicon dioxide	60676-86-0	540.879	34.56	43.20	345626	432032
lead finish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6171	6171
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.122	0.01		78	
	noble metal	silver	7440-22-4	0.153	0.01		98	
	non noble metal	lead	7439-92-1	5.834	0.37	0.39	3728	3904
glue	plastics	Polyimide	26023-21-2	0.124	0.01	0.01	79	79
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		350	
	non noble metal	copper	7440-50-8	547.666	35.00	35.05	349963	350418
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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